

March 25 WG 4, RF Power Coupler

Time	Subject	Speaker	Status
	Copper plating	90 minutes, Chair by Moeller	
8:30	Copper plating specifications, XFEL, LCLS-II, KEK, ERL Cornell, CERN	Introduction by Wolf-Dietrich Moeller (15 min.)	Confirmed
	Copper plating methodes	S. Calatroni, CERN (10 min.)	Confirmed
	Thermal simulations, pulsed CW, XFEL, others	Denis Kostin, DESY (10 min.)	Confirmed
	Investigation methodes, destructive and non-destructive	A. Ermakov (10 min.)	Confirmed
	Real defects, examples, classification at XFEL	Walid Kaabi, LAL (10 min.)	Confirmed
	Experience with defects in copper plating at HTS (SLAC/CPI/FNAL ILC collaboration)	Ken Premo, FNAL (10 min.)	Confirmed
	Method and experience of copper plating at Toshiba	Osamu Yushiro, Toshiba (10 min.)	Confirmed
	Copper plating issues at Cornell	Vadim Veshcherevich, Cornell (10 min.)	Confirmed
	QC during mass production	Discussion lead by Wolf-Dietrich Moeller (15 min.)	Confirmed
10:10	Coffee (20 min.)		
10:30	Power coupler preparation before RF conditioning	60 minutes, Chair by Kako	
	IFMIF coupler	Slides supplied by Hassen Jenhani, CEA (10 min.)	Confirmed
	XFEL coupler	Walid Kaabi, LAL (10 min.)	Confirmed
	KEK-cERL, ML coupler	H. Sakai, KEK (10 min.)	Confirmed
	TTF3-SLAC/FNAL coupler	K. Premo, FNAL (10 min.)	Confirmed
	SPIRAL2 coupler	Y. G-Martinez, LPSC (10 min.)	Confirmed
	What is the best preparation procedure?	Discussion lead by E. Kako (10 min.)	Confirmed
11:30	New power coupler design	60 minutes, Chair by Kako	
	TTF-3 coupler modification for LCLS-II CW operation	Nikolay Solyak, FNAL (10 min.)	Confirmed
	ANL coupler for FRIB	Slides supplied by M. Kelly, ANL (10 min.)	Confirmed
	Coupler designed with HE 11 mode at SLAC	Slides supplied by Chen Xu, SLAC (10 min.)	Received
	CW coupler for BerlinPro/HZB	Vasim Khan, HZB (10 min.)	Confirmed
	CW coupler for Cornell ERL	Vadim Veshcherevich, Cornell (10 min.)	Confirmed
	ESS coupler design	Christine Darve, ESS (10 min.)	Confirmed
12:30	Lunch		